



Material Content Data Sheet



Sales Product Name		TLE6288R		Issued		28. August 2013			
MA#		MA000985216							
Package		PG-DSO-36-54		Weight*		2054.44 mg			
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	34.977	1.70	1.70	17025	17025	
leadframe	inorganic material	phosphorus	7723-14-0	0.383	0.02		186		
	non noble metal	zinc	7440-66-6	1.533	0.07		746		
	non noble metal	iron	7439-89-6	30.652	1.49		14920		
	non noble metal	copper	7440-50-8	1244.598	60.58	62.16	605809	621661	
wire	non noble metal	copper	7440-50-8	1.967	0.10	0.10	958	958	
encapsulation	organic material	carbon black	1333-86-4	1.407	0.07		685		
	plastics	epoxy resin	-	64.721	3.15		31503		
	inorganic material	silicondioxide	60676-86-0	637.363	31.02	34.24	310236	342424	
leadfinish	non noble metal	tin	7440-31-5	16.150	0.79	0.79	7861	7861	
plating	noble metal	silver	7440-22-4	0.741	0.04	0.04	361	361	
solder	noble metal	silver	7440-22-4	0.299	0.01		146		
	non noble metal	tin	7440-31-5	0.199	0.01		97		
	non noble metal	lead	7439-92-1	19.450	0.95	0.97	9467	9710	
*deviation	< 10%					Sum in total:	100.00		1000000

Important Remarks:

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